

## SMA Plastic-Encapsulate Diodes

### Super Fast Recovery Rectifier Diodes

#### Features:

- $I_{F(AV)}$  1A
- $V_{RRM}$  200V-600V
- High surge current capability
- Polarity: Color band denotes cathode

#### Applications:

- Rectifier

#### Marking

- MURS1X0

X : From 2 to 6

#### Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	KMUR		
				S120	S140	S160
Repetitive Peak Reverse Voltage	$V_{RRM}$	V		200	400	600
Maximum RMS Voltage	$V_{RMS}$	V		140	280	420
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave , Resistance load , $T_a=120^{\circ}C$	1.0		
Surge(Non-repetitive)Forward Current	$I_{FSM}$	A	60Hz Half-sine wave , 1 cycle , $T_a=25^{\circ}C$	35		
Operation Junction and Storage Temperature Range	$T_J, T_{STG}$	$^{\circ}C$		-55 ~ +175		

#### Electrical Characteristics (T=25 °C Unless otherwise specified )

Item	Symbol	Unit	Test Condition	KMUR		
				S120	S140	S160
Peak Forward Voltage	$V_{FM}$	V	$I_{FM}=1.0A$	0.875	1.25	
Peak Reverse Current	$I_{RRM1}$		$V_{RM}=V_{RRM}$		$T_a = 25^{\circ}C$	
	$I_{RRM2}$				$T_a = 125^{\circ}C$	
Reverse recovery time	$t_{rr}$	ns	$I_F=0.5A, I_R=1.0A$ $I_{rr}=0.25A$	25	50	
Thermal Resistance(Typical)	$R_{\theta J-A}$	$^{\circ}C/W$	Between junction and ambient	60		
	$R_{\theta J-L}$		Between junction and lead	20		

#### Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

SMA



### Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

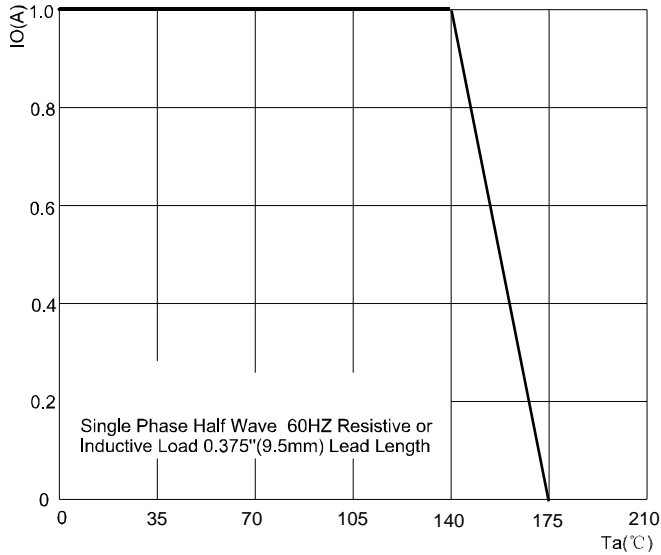


FIG.2: MAXIMUM NON-REPETITIVE FORWARD URGE CURRENT

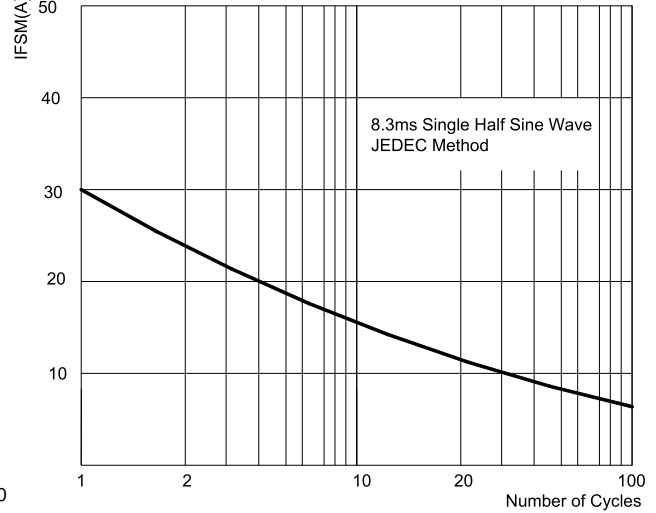


FIG.3: TYPICAL FORWARD CHARACTERISTICS

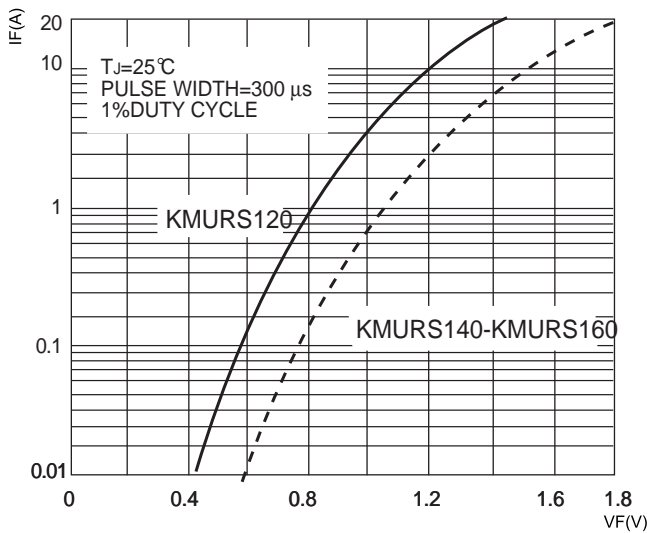


FIG.4: TYPICAL REVERSE CHARACTERISTICS

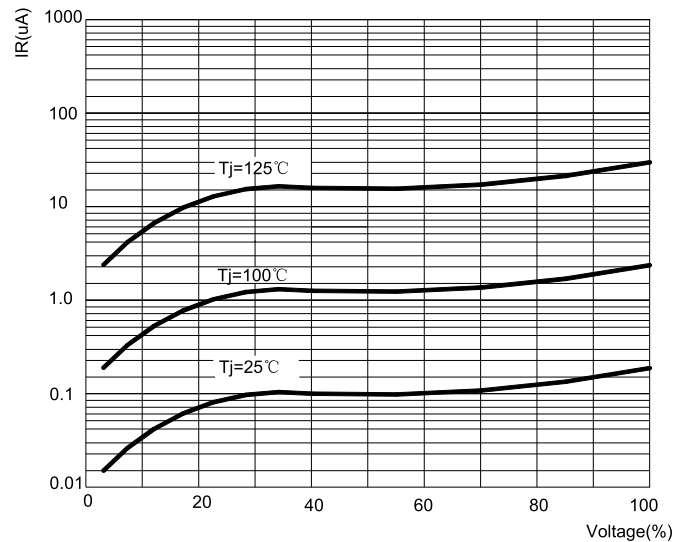
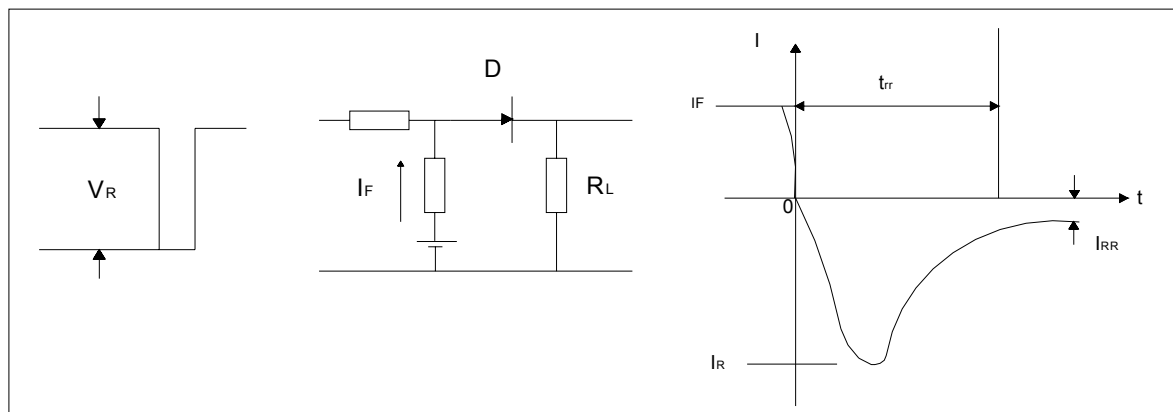
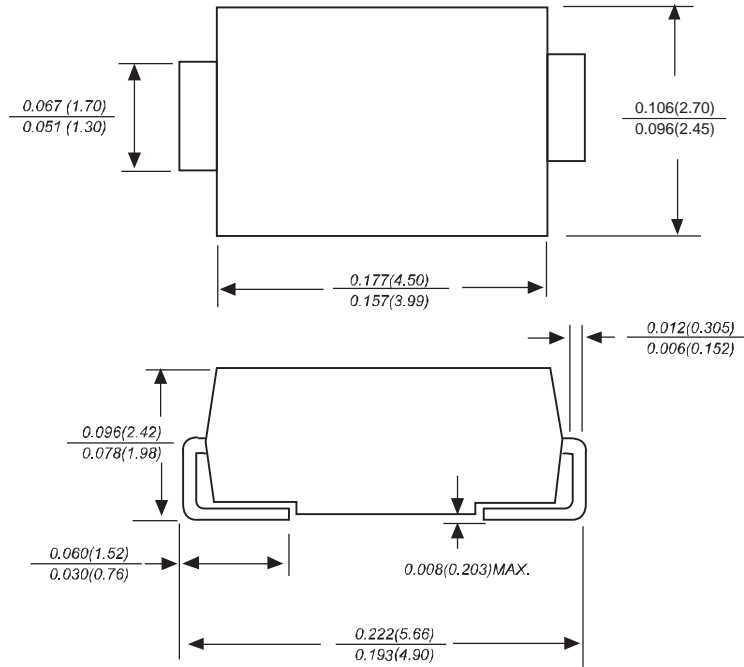


FIG.5: Diagram of circuit and Testing wave form of reverse recovery time

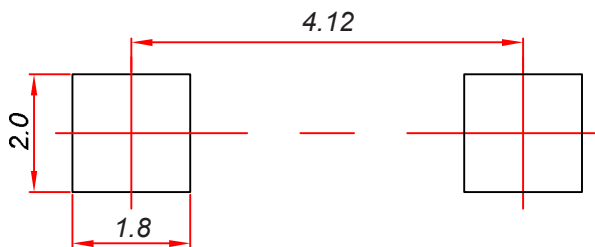


### SMA Package Outline Dimensions



Dimensions in inches and (millimeters)

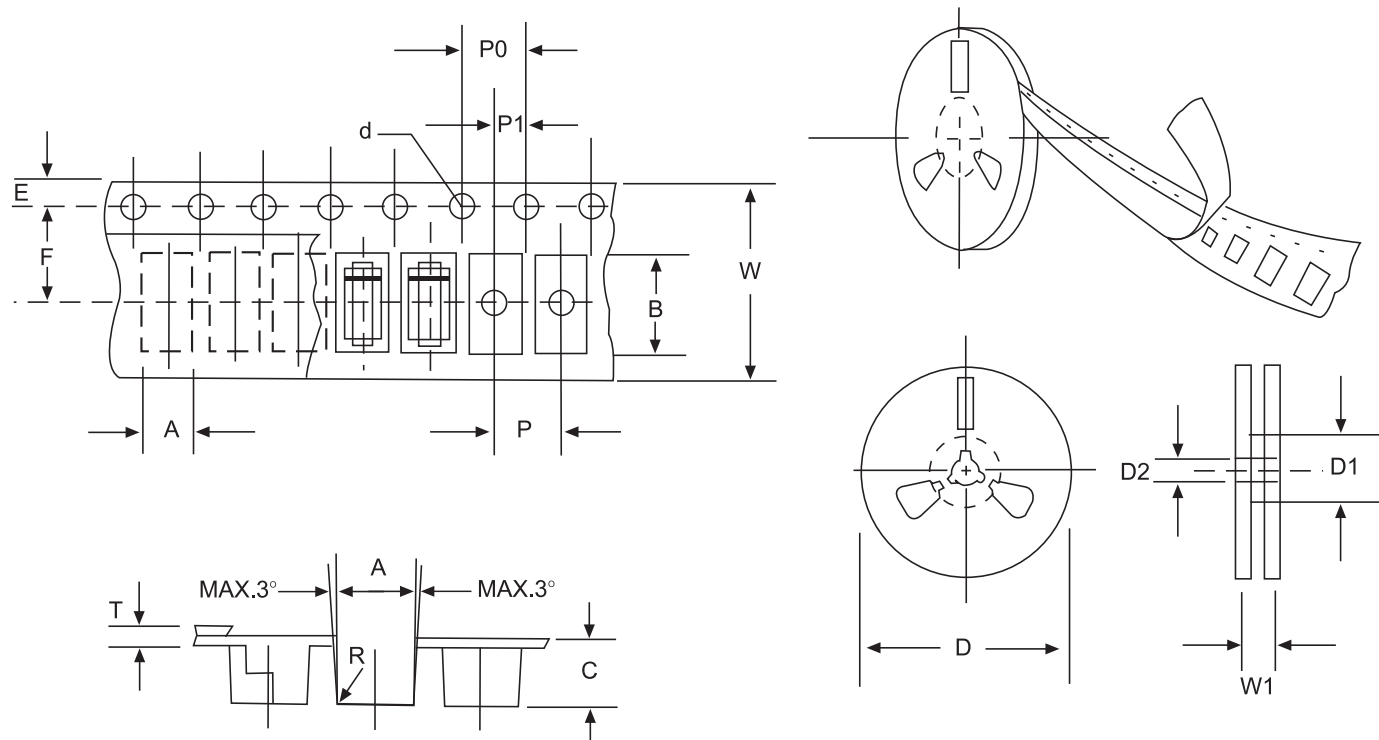
### SMA Suggested Pad Layout



**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05\text{mm}$ .
3. The pad layout is for reference purposes only.

**Reel Taping Specifications For Surface Mount Devices- SMA**



**FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING**

ITEM	SYMBOL	SMA mm(inch)
Carrier width	A	2.79±0.1(0.110±0.004)
Carrier length	B	5.33±0.1(0.210±0.004)
Carrier depth	C	2.36±0.1(0.093±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	279±2.0 (11± 0.079)
Reel inner diameter	D1	75 ±1.0 ( 2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Stroket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217 ±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Total tape thickness	T	0.28±0.02(0.011 ±0.0008 )
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.